Abstracts

Low cost UTSi technology for RF wireless applications

M. Megahed, M. Burgener, J. Cable, R. Benton, D. Staab, M. Stuber, P. Dennies and R. Reedy. "Low cost UTSi technology for RF wireless applications." 1998 MTT-S International Microwave Symposium Digest 98.2 (1998 Vol. II [MWSYM]): 981-984.

Ultra Thin Silicon (UTSi) IC technology has been developed for RF, analog, and digital signal applications. The technology is based on low cost CMOS VLSI technology with fully integrated passive components. The insulating substrate provides high isolation and high quality passive components, paving the way for on-chip matching elements. For the first time, excellent high-speed/high-frequency performance is simultaneously demonstrated by the highly integrated UTSi technology.

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